

TLV493D-A1B6

3D Magnetic Sensor

Early Problem Notification

July 2015

Products affected

The described issues have been found on early Engineering Samples of TLV493D-A1B6. A list of the potentially affected products is given in **Table 1**.

Table 1Potentially affected products

Product name	Ordering code	Marking	Package
TLV493D-A1B6	SP001286056	SA (Engineering Samples)	TSOP-6

Communication Error

Communication Error

Problem Description

A communication error can occur during operation. Every mode can be affected.

A communication error can be detected by:

- No ACK from sensor after READ command
- Interruption of communication by sensor

Corrective Action

In order to avoid communication errors please implement following application circuit:

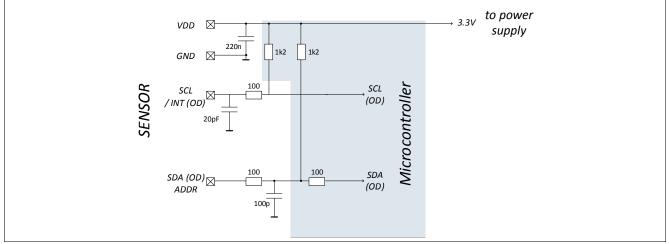


Figure 1





ADC - hang up in Master Controlled or Fast Mode

ADC - hang up in Master Controlled or Fast Mode

Problem Description

In the Master Controlled Mode (MCM) or the Fast Mode (FM) the ADC conversion may hang up in early engineering samples.

A Hang up can be detected by:

• Frame Counter (FRM) counter stucks and does not increment anymore

Corrective Action

Operating Mode, Sensor used in polling mode¹⁾ / **master controlled mode**

- 1. Detect a non incrementing frame counter
- 2. Send general address 0x00 to reset the sensor (see also power-up/reset behaviour in product data sheet)
- 3. Re-configure to Master controlled Mode

or Operating Mode, Sensor used in Interrupt mode (Fast or Master controlled Mode)

- 1. Use a system watchdog to detect a missing interrupt
- 2. Optional: detect a non incrementing frame counter
- 3. Send general address 0x00 to reset the sensor (see also power-up/reset behaviour in product data sheet)
- 4. Re-configure to desired Fast or Master controlled Mode

¹⁾ polling:= no /Int is issued, uC reads out sensor in fixed periods

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